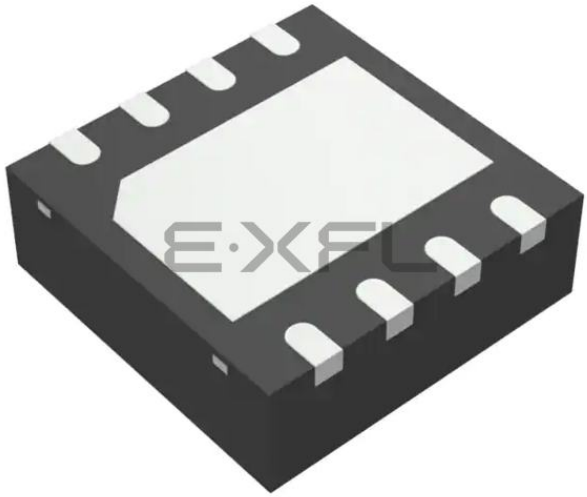

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	5
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	8-VDFN Exposed Pad
Supplier Device Package	8-DFN-S (6x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12lc672-04i-mf

3.1 Clocking Scheme/Instruction Cycle

The clock input (from OSC1) is internally divided by four to generate four non-overlapping quadrature clocks, namely Q1, Q2, Q3 and Q4. Internally, the program counter (PC) is incremented every Q1, and the instruction is fetched from the program memory and latched into the instruction register in Q4. The instruction is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow is shown in Figure 3-2.

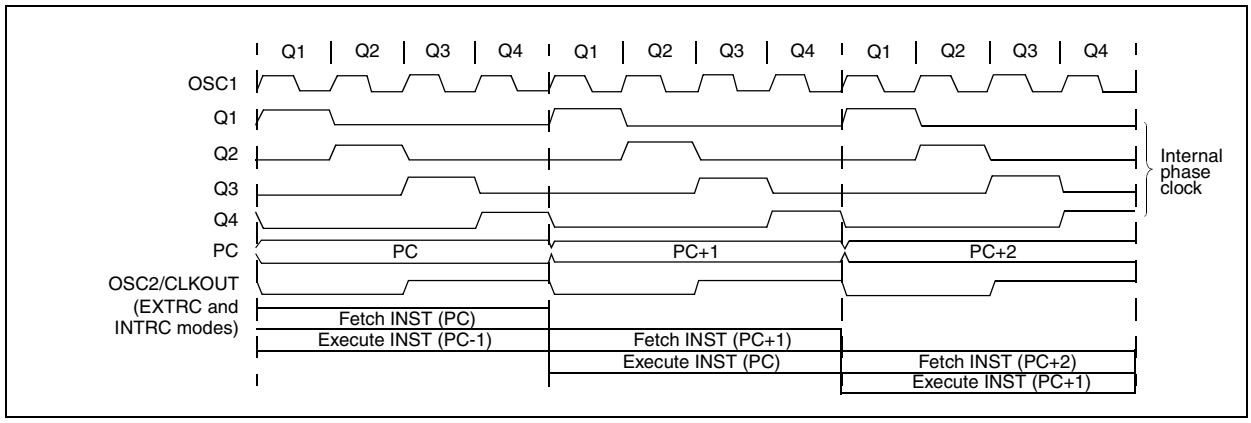
3.2 Instruction Flow/Pipelining

An “Instruction Cycle” consists of four Q cycles (Q1, Q2, Q3 and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle, while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (i.e., `GOTO`), then two cycles are required to complete the instruction (Example 3-1).

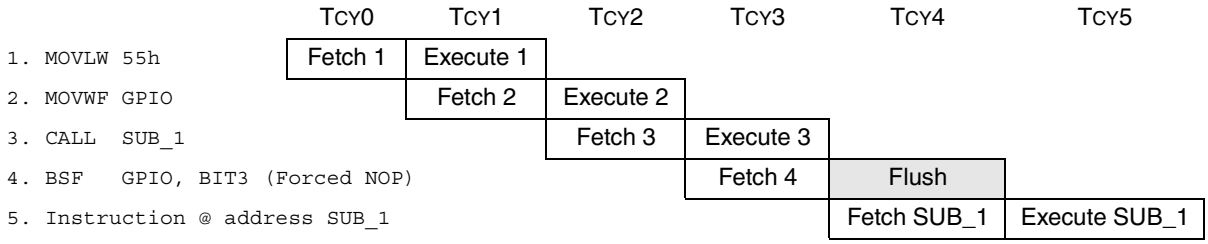
A fetch cycle begins with the program counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the “Instruction Register" (IR) in cycle Q1. This instruction is then decoded and executed during the Q2, Q3, and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

FIGURE 3-2: CLOCK/INSTRUCTION CYCLE

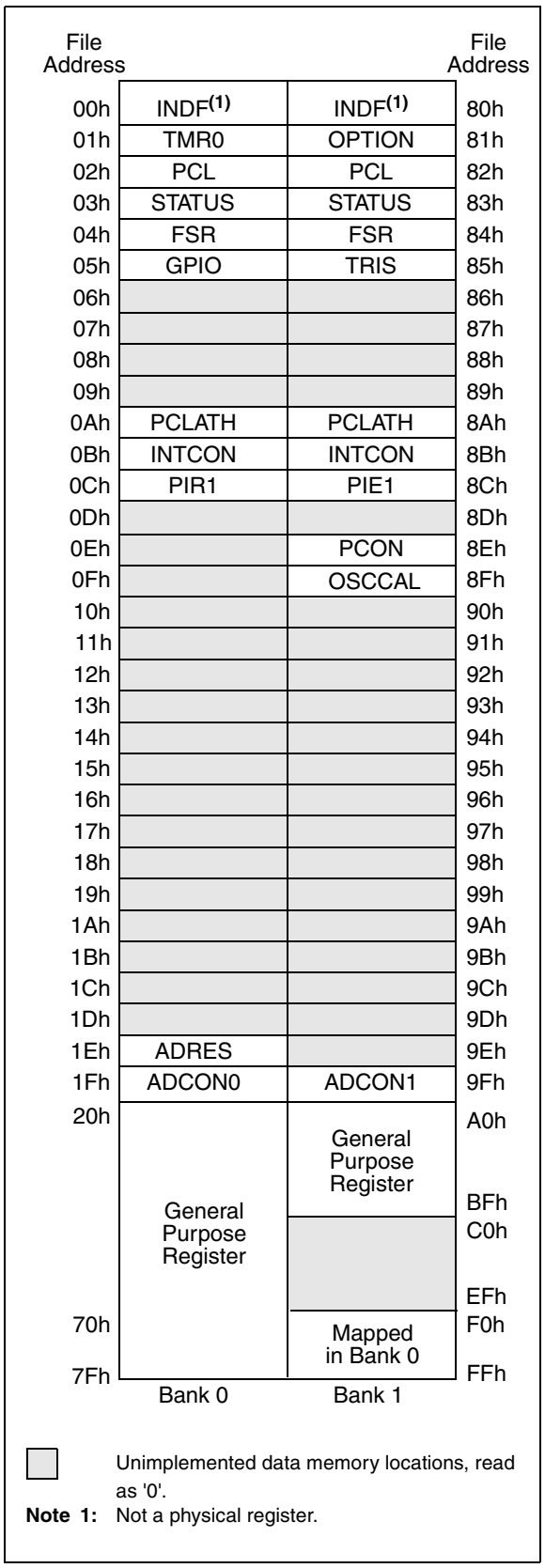


EXAMPLE 3-1: INSTRUCTION PIPELINE FLOW



All instructions are single cycle, except for any program branches. These take two cycles since the fetched instruction is “flushed” from the pipeline while the new instruction is being fetched and then executed.

FIGURE 4-2: PIC12C67X REGISTER FILE MAP



4.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers are registers used by the CPU and Peripheral Modules for controlling the desired operation of the device. These registers are implemented as static RAM.

The Special Function Registers can be classified into two sets (core and peripheral). Those registers associated with the “core” functions are described in this section, and those related to the operation of the peripheral features are described in the section of that peripheral feature.

TABLE 4-1: PIC12C67X SPECIAL FUNCTION REGISTER SUMMARY

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other Resets(3)
Bank 0											
00h(1)	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	0000 0000
01h	TMR0	Timer0 module's register								xxxx xxxx	uuuu uuuu
02h(1)	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000
03h(1)	STATUS	IRP(4)	RP1(4)	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	000q quuu
04h(1)	FSR	Indirect data memory address pointer								xxxx xxxx	uuuu uuuu
05h	GPIO	SCL(5)	SDA(5)	GP5	GP4	GP3	GP2	GP1	GP0	11xx xxxx	11uu uuuu
06h	—	Unimplemented								—	—
07h	—	Unimplemented								—	—
08h	—	Unimplemented								—	—
09h	—	Unimplemented								—	—
0Ah(1,2)	PCLATH	—	—	—	Write Buffer for the upper 5 bits of the Program Counter					---0 0000	---0 0000
0Bh(1)	INTCON	GIE	PEIE	T0IE	INTE	GPIE	T0IF	INTF	GPIF	0000 000x	0000 000u
0Ch	PIR1	—	ADIF	—	—	—	—	—	—	-0-- ----	-0-- ----
0Dh	—	Unimplemented								—	—
0Eh	—	Unimplemented								—	—
0Fh	—	Unimplemented								—	—
10h	—	Unimplemented								—	—
11h	—	Unimplemented								—	—
12h	—	Unimplemented								—	—
13h	—	Unimplemented								—	—
14h	—	Unimplemented								—	—
15h	—	Unimplemented								—	—
16h	—	Unimplemented								—	—
17h	—	Unimplemented								—	—
18h	—	Unimplemented								—	—
19h	—	Unimplemented								—	—
1Ah	—	Unimplemented								—	—
1Bh	—	Unimplemented								—	—
1Ch	—	Unimplemented								—	—
1Dh	—	Unimplemented								—	—
1Eh	ADRES	A/D Result Register								xxxx xxxx	uuuu uuuu
1Fh	ADCON0	ADCS1	ADCS0	reserved	CHS1	CHS0	GO/$\overline{DONE}$	reserved	ADON	0000 0000	0000 0000

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented read as '0'.
Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from either bank.

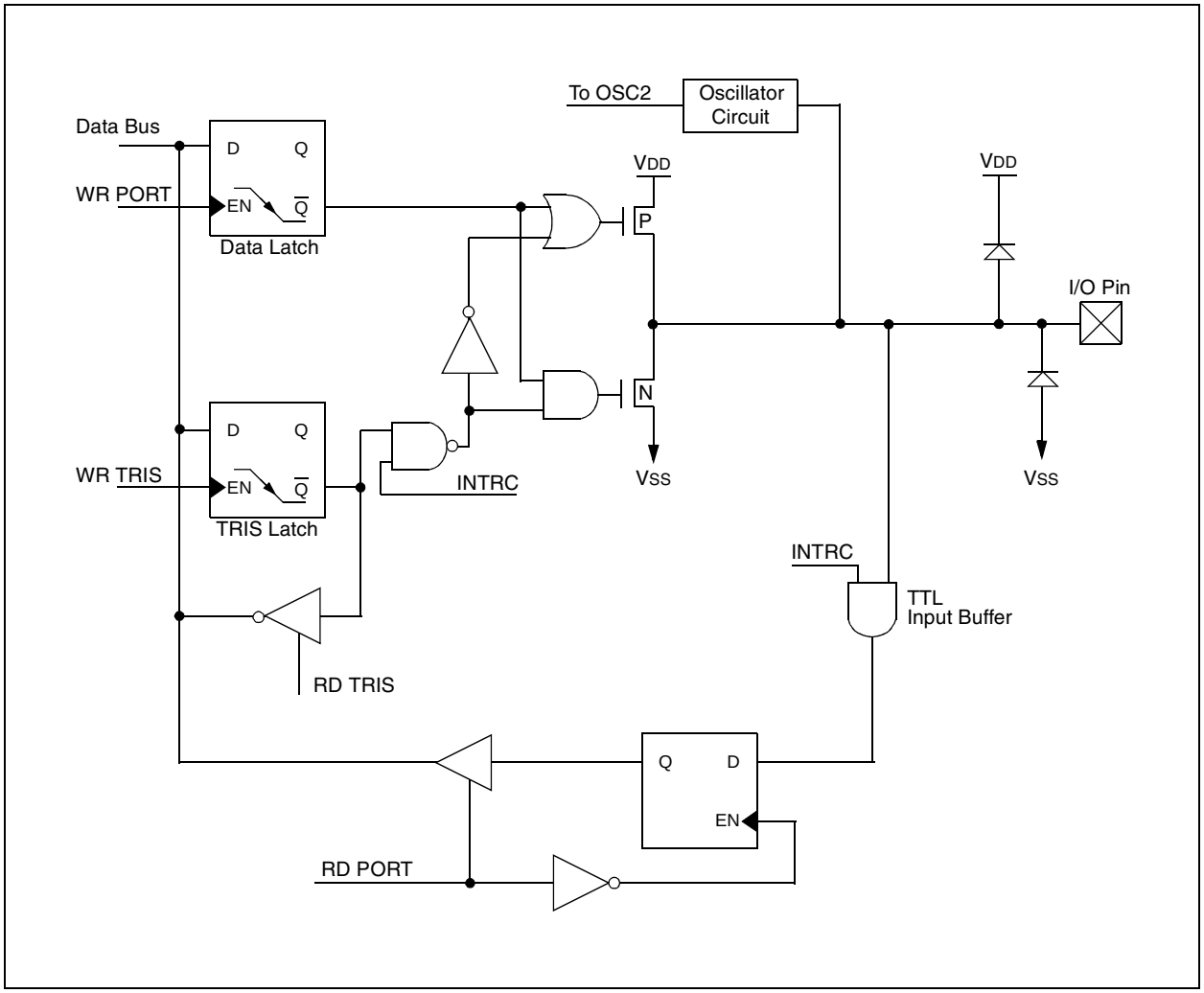
2: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for the PC<12:8> whose contents are transferred to the upper byte of the program counter.

3: Other (non power-up) resets include external reset through $\overline{MCLR}$ and Watchdog Timer Reset.

4: The IRP and RP1 bits are reserved on the PIC12C67X; always maintain these bits clear.

5: The SCL (GP7) and SDA (GP6) bits are unimplemented on the PIC12C671/672 and read as '0'.

FIGURE 5-5: BLOCK DIAGRAM OF GP5/OSC1/CLKIN PIN



6.3 Write Operations

6.3.1 BYTE WRITE

Following the start signal from the processor, the device code (4 bits), the don't care bits (3 bits), and the R/$\overline{W}$ bit (which is a logic low) are placed onto the bus by the processor. This indicates to the addressed EEPROM that a byte with a word address will follow after it has generated an acknowledge bit during the ninth clock cycle. Therefore, the next byte transmitted by the processor is the word address and will be written into the address pointer. Only the lower four address bits are used by the device, and the upper four bits are don't cares. If the address byte is acknowledged, the processor will then transmit the data word to be written into the addressed memory location. The memory acknowledges again and the processor generates a stop condition. This initiates the internal write cycle, and during this time will not generate acknowledge signals. After a byte write command, the internal address counter will not be incremented and will point to the same address location that was just written. If a stop bit sequence is transmitted to the device at any point in the write command sequence before the entire sequence is complete, then the command will abort and no data will be written. If more than 8 data bits are transmitted before the stop bit sequence is sent, then the device will clear the previously loaded byte and begin loading the data buffer again. If more than one data byte is transmitted to the device and a stop bit is sent before a full eight data bits have been transmitted, then the write command will abort and no data will be written. The EEPROM memory employs a V_{CC} threshold detector circuit, which disables the internal erase/write logic if the V_{CC} is below minimum V_{DD}. Byte write operations must be preceded and immediately followed by a bus not busy bus cycle where both SDA and SCL are held high. (See Figure 6-7 for Byte Write operation.)

6.4 Acknowledge Polling

Since the EEPROM will not acknowledge during a write cycle, this can be used to determine when the cycle is complete (this feature can be used to maximize bus throughput). Once the stop condition for a write command has been issued from the processor, the device initiates the internally timed write cycle. ACK polling can be initiated immediately. This involves the processor sending a start condition followed by the control byte for a write command (R/$\overline{W}$ = 0). If the device is still busy with the write cycle, then no ACK will be returned. If no ACK is returned, then the start bit and control byte must be re-sent. If the cycle is complete, then the device will return the ACK and the processor can then proceed with the next read or write command. (See Figure 6-6 for flow diagram.)

FIGURE 6-6: ACKNOWLEDGE POLLING FLOW

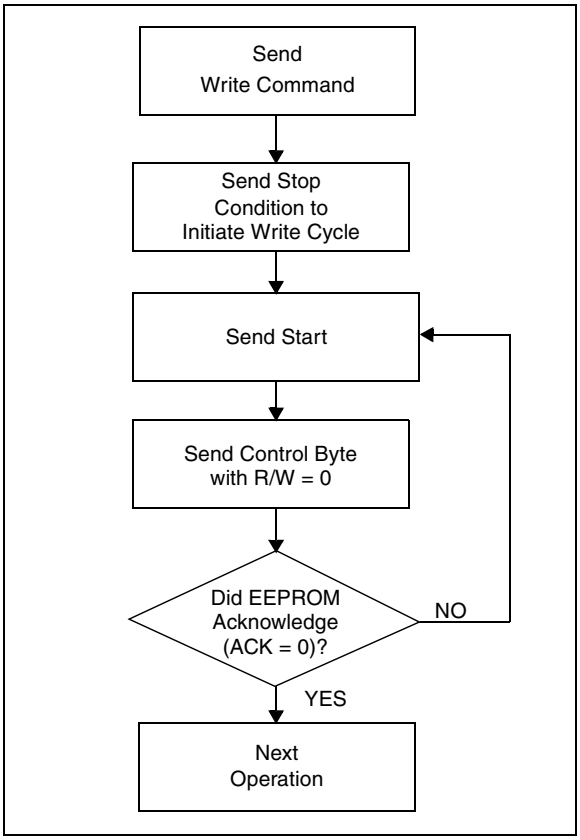
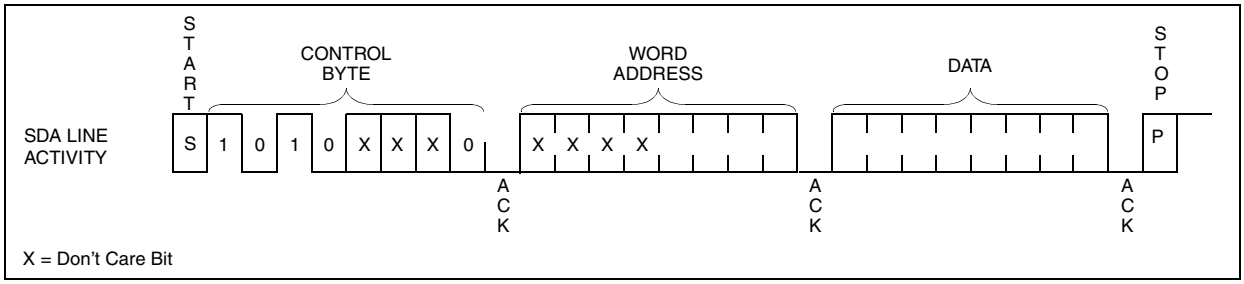


FIGURE 6-7: BYTE WRITE



6.5 Read Operations

Read operations are initiated in the same way as write operations with the exception that the R/$\overline{W}$ bit of the EEPROM address is set to one. There are three basic types of read operations; current address read, random read and sequential read.

6.5.1 CURRENT ADDRESS READ

The EEPROM contains an address counter that maintains the address of the last word accessed, internally incremented by one. Therefore, if the previous read access was to address n, the next current address read operation would access data from address n + 1. Upon receipt of the EEPROM address with the R/$\overline{W}$ bit set to one, the EEPROM issues an acknowledge and transmits the 8-bit data word. The processor will not acknowledge the transfer, but does generate a stop condition and the EEPROM discontinues transmission (Figure 6-8).

6.5.2 RANDOM READ

Random read operations allow the processor to access any memory location in a random manner. To perform this type of read operation, first the word address must be set. This is done by sending the word address to the EEPROM as part of a write operation. After the word address is sent, the processor generates a start condition following the acknowledge. This terminates the write operation, but not before the internal address pointer is set. Then the processor issues the control byte again, but with the R/$\overline{W}$ bit set to a one. The EEPROM will then issue an acknowledge and transmits the 8-bit data word. The processor will not acknowledge the transfer, but does generate a stop condition and the EEPROM discontinues transmission (Figure 6-9). After this command, the internal address counter will point to the address location following the one that was just read.

6.5.3 SEQUENTIAL READ

Sequential reads are initiated in the same way as a random read, except that after the device transmits the first data byte, the processor issues an acknowledge as opposed to a stop condition in a random read. This directs the EEPROM to transmit the next sequentially addressed 8-bit word (Figure 6-10).

To provide sequential reads, the EEPROM contains an internal address pointer, which is incremented by one at the completion of each read operation. This address pointer allows the entire memory contents to be serially read during one operation.

FIGURE 6-8: CURRENT ADDRESS READ

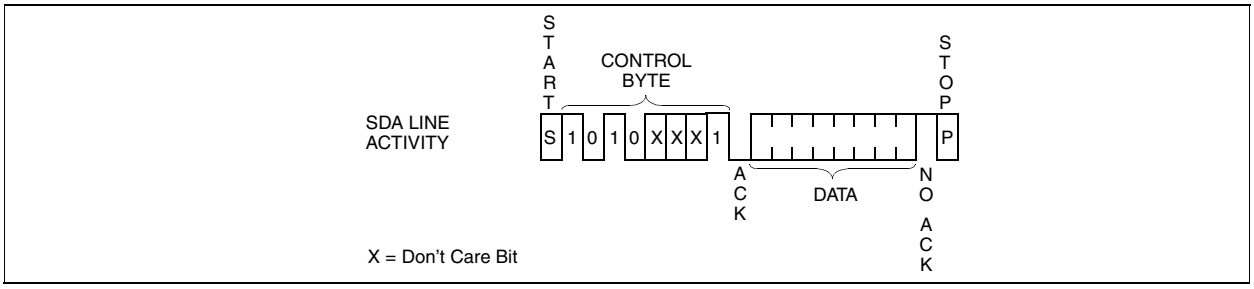


FIGURE 6-9: RANDOM READ

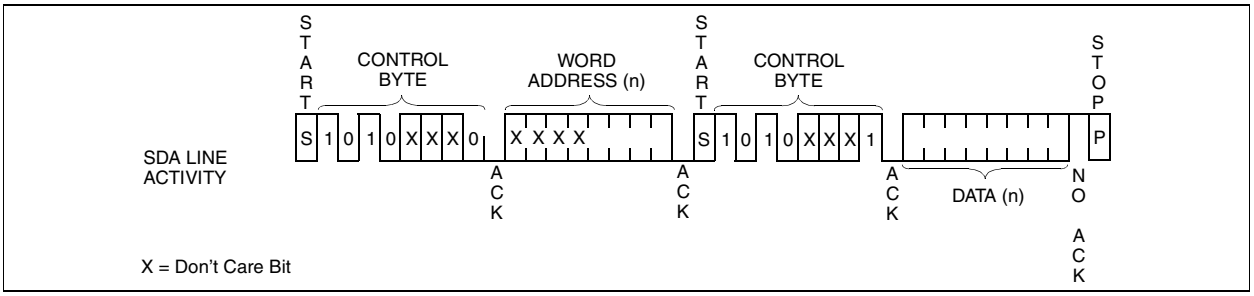
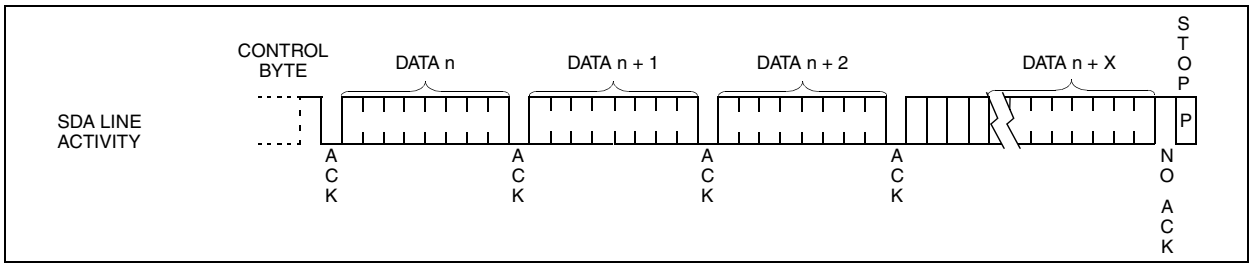


FIGURE 6-10: SEQUENTIAL READ



NOTES:

7.2 Using Timer0 with an External Clock

When an external clock input is used for Timer0, it must meet certain requirements. The requirements ensure the external clock can be synchronized with the internal phase clock (TOSC). Also, there is a delay in the actual incrementing of Timer0 after synchronization.

7.2.1 EXTERNAL CLOCK SYNCHRONIZATION

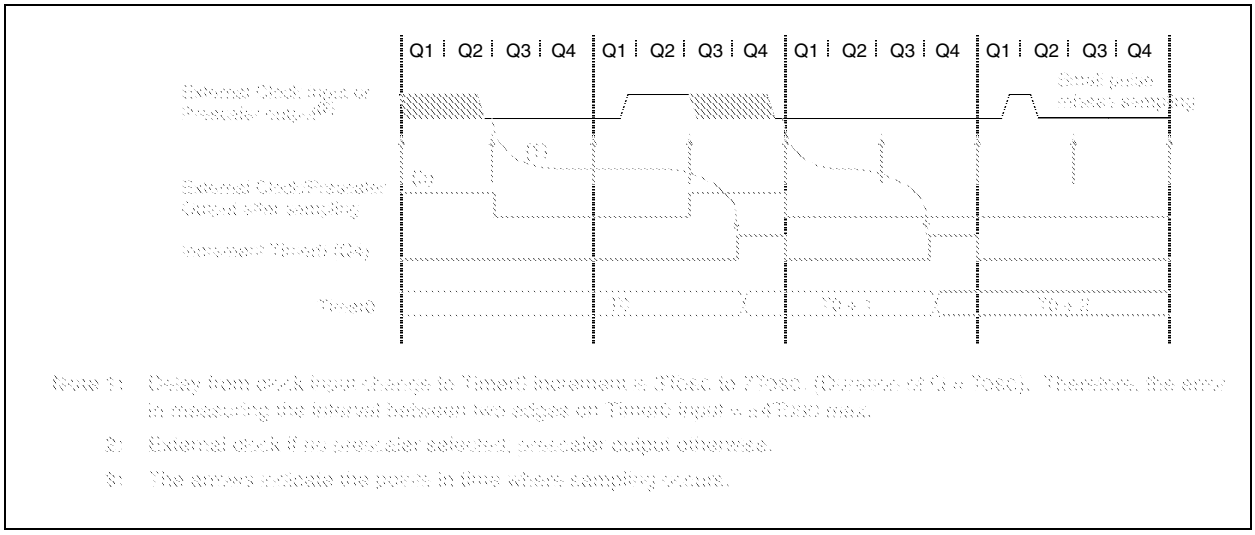
When no prescaler is used, the external clock input is used as the clock source. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 7-5). Therefore, it is necessary for T0CKI to be high for at least 2TOSC (and a small RC delay of 20 ns) and low for at least 2TOSC (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

When a prescaler is used, the external clock input is divided by the asynchronous ripple-counter type prescaler, so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple-counter must be taken into account. Therefore, it is necessary for T0CKI to have a period of at least 4TOSC (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T0CKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

7.2.2 TMR0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the Timer0 module is actually incremented. Figure 7-5 shows the delay from the external clock edge to the timer incrementing.

FIGURE 7-5: TIMER0 TIMING WITH EXTERNAL CLOCK



Note 1: Delay from clock input change to Timer0 increment is 3Tosc to 7Tosc. (Duration of Q = Tosc). Therefore, the error in measuring the interval between two edges on Timer0 input = ±4Tosc max.

2: External clock if no prescaler selected, prescaler output otherwise.

3: The arrows indicate the points in time where sampling occurs.

8.1 A/D Sampling Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 8-2. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), see Figure 8-2. **The maximum recommended impedance for analog sources is 10 kΩ.** After the analog input channel is selected (changed), this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, Equation 8-1 may be used. This equation assumes that 1/2 LSb error is used (512 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

EQUATION 8-1: A/D MINIMUM CHARGING TIME

$V_{HOLD} = (V_{REF} - (V_{REF}/512)) \bullet (1 - e^{(-Tc/C_{HOLD}(R_{IC} + R_{SS} + R_S))})$

or

$Tc = -(51.2\ pF)(1\ k\Omega + R_{SS} + R_S)\ \ln(1/511)$

Example 8-1 shows the calculation of the minimum required acquisition time TACQ. This calculation is based on the following system assumptions.

Rs = 10 kΩ

1/2 LSb error

VDD = 5V → Rss = 7 kΩ

Temp (system max.) = 50°C

VHOLD = 0 @ t = 0

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

4: After a conversion has completed, a 2.0 TAD delay must complete before acquisition can begin again. During this time, the holding capacitor is not connected to the selected A/D input channel.

EXAMPLE 8-1: CALCULATING THE MINIMUM REQUIRED SAMPLE TIME

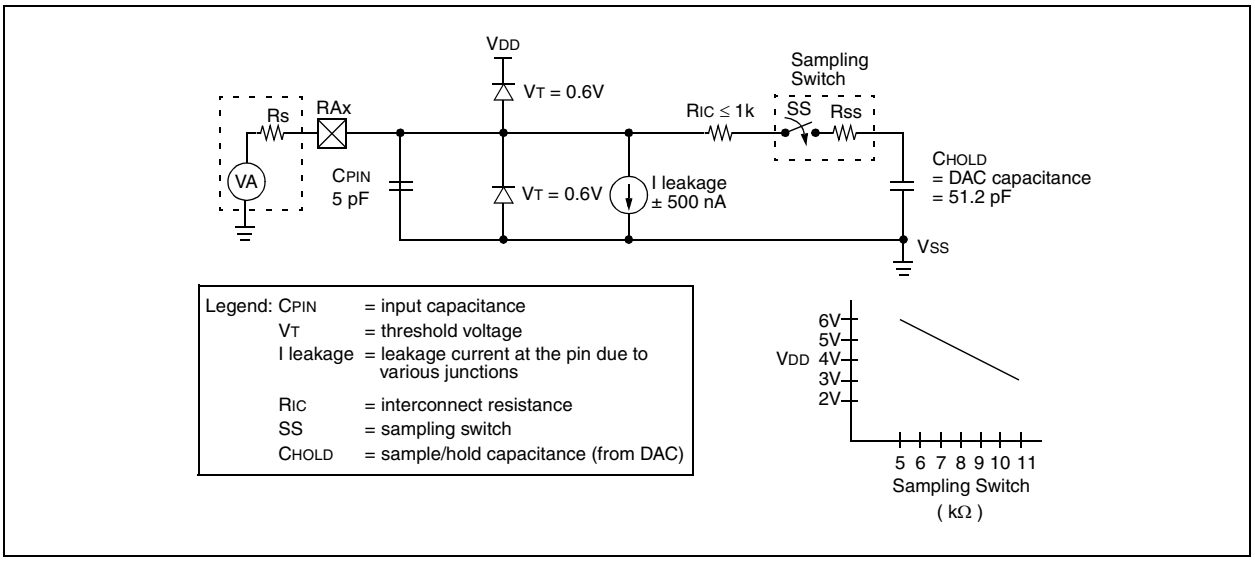
TACQ = Internal Amplifier Settling Time +
Holding Capacitor Charging Time +
Temperature Coefficient

TACQ = 5 μs + Tc + [(Temp - 25°C)(0.05 μs/°C)]

TC = -CHOLD (RIC + RSS + RS) ln(1/512)
-51.2 pF (1 kΩ + 7 kΩ + 10 kΩ) ln(0.0020)
-51.2 pF (18 kΩ) ln(0.0020)
-0.921 μs (-6.2146)
5.724 μs

TACQ = 5 μs + 5.724 μs + [(50°C - 25°C)(0.05 μs/°C)]
10.724 μs + 1.25 μs
11.974 μs

FIGURE 8-2: ANALOG INPUT MODEL



9.4 Power-on Reset (POR), Power-up Timer (PWRT) and Oscillator Start-up Timer (OST)

9.4.1 POWER-ON RESET (POR)

The on-chip POR circuit holds the chip in reset until VDD has reached a high enough level for proper operation. To take advantage of the POR, just tie the $\overline{MCLR}$ pin through a resistor to VDD. This will eliminate external RC components usually needed to create a Power-on Reset. A maximum rise time for VDD is specified. See Electrical Specifications for details.

When the device starts normal operation (exits the reset condition), device operating parameters (voltage, frequency, temperature, ...) must be met to ensure operation. If these conditions are not met, the device must be held in reset until the operating conditions are met.

For additional information, refer to Application Note AN607, "*Power-up Trouble Shooting*."

9.4.2 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 72 ms nominal time-out on power-up only, from the POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in reset as long as the PWRT is active. The PWRT's time delay allows VDD to rise to an acceptable level. A configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip to chip due to VDD, temperature and process variation. See Table 11-4.

9.4.3 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-up Timer (OST) provides 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

9.4.4 TIME-OUT SEQUENCE

On power-up, the Time-out Sequence is as follows: first, PWRT time-out is invoked after the POR time delay has expired; then, OST is activated. The total time-out will vary, based on oscillator configuration and the status of the PWRT. For example, in RC mode with the PWRT disabled, there will be no time-out at all. Figure 9-7, Figure 9-8, and Figure 9-9 depict time-out sequences on power-up.

Since the time-outs occur from the POR pulse, if $\overline{MCLR}$ is kept low long enough, the time-outs will expire. Then bringing $\overline{MCLR}$ high will begin execution immediately (Figure 9-9). This is useful for testing purposes or to synchronize more than one PIC12C67X device operating in parallel.

9.4.5 POWER CONTROL (PCON)/STATUS REGISTER

The Power Control/Status Register, PCON (address 8Eh), has one bit. See Register 4-6 for register.

Bit1 is $\overline{POR}$ (Power-on Reset). It is cleared on a Power-on Reset and is unaffected otherwise. The user sets this bit following a Power-on Reset. On subsequent resets, if POR is '0', it will indicate that a Power-on Reset must have occurred.

TABLE 9-4: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up		Wake-up from SLEEP
	$\overline{PWRTE}$ = 0	$\overline{PWRTE}$ = 1	
XT, HS, LP	72 ms + 1024TOSC	1024TOSC	1024TOSC
INTRC, EXTRC	72 ms	—	—

TABLE 9-5: STATUS/PCON BITS AND THEIR SIGNIFICANCE

$\overline{POR}$	$\overline{TO}$	$\overline{PD}$	
0	1	1	Power-on Reset
0	0	x	Illegal, $\overline{TO}$ is set on $\overline{POR}$
0	x	0	Illegal, $\overline{PD}$ is set on $\overline{POR}$
1	0	u	WDT Reset
1	0	0	WDT Wake-up
1	u	u	$\overline{MCLR}$ Reset during normal operation
1	1	0	$\overline{MCLR}$ Reset during SLEEP or interrupt wake-up from SLEEP

Legend: u = unchanged, x = unknown.

9.5.1 TMR0 INTERRUPT

An overflow (FFh → 00h) in the TMR0 register will set flag bit T0IF (INTCON<2>). The interrupt can be enabled/disabled by setting/clearing enable bit T0IE (INTCON<5>) (Section 7.0). The flag bit T0IF (INTCON<2>) will be set, regardless of the state of the enable bits. If used, this flag must be cleared in software.

9.5.2 INT INTERRUPT

External interrupt on GP2/INT pin is edge triggered; either rising if bit INTEDG (OPTION<6>) is set, or falling, if the INTEDG bit is clear. When a valid edge appears on the GP2/INT pin, flag bit INTF (INTCON<1>) is set. This interrupt can be disabled by clearing enable bit INTE (INTCON<4>). Flag bit INTF must be cleared in software in the interrupt service routine before re-enabling this interrupt. The INT interrupt can wake-up the processor from SLEEP, if bit INTE was set prior to going into SLEEP. The status of global interrupt enable bit GIE decides whether or not the processor branches to the interrupt vector following wake-up. See Section 9.8 for details on SLEEP mode.

9.5.3 GPIO INTCON CHANGE

An input change on GP3, GP1 or GP0 sets flag bit GPIF (INTCON<0>). The interrupt can be enabled/disabled by setting/clearing enable bit GPIE (INTCON<3>) (Section 5.1) . This flag bit GPIF (INTCON<0>) will be set, regardless of the state of the enable bits. If used, this flag must be cleared in software.

9.6 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt (i.e., W register and STATUS register). This will have to be implemented in software.

Example 9-1 shows the storing and restoring of the STATUS and W registers. The register, W_TEMP, must be defined in both banks and must be defined at the same offset from the bank base address (i.e., if W_TEMP is defined at 0x20 in bank 0, it must also be defined at 0xA0 in bank 1).

Example 9-2 shows the saving and restoring of STATUS and W using RAM locations 0x70 - 0x7F. W_TEMP is defined at 0x70 and STATUS_TEMP is defined at 0x71.

The example:

a) Stores the W register.
b) Stores the STATUS register in bank 0.
c) Executes the ISR code.
d) Restores the STATUS register (and bank select bit).
e) Restores the W register.
f) Returns from interrupt.

EXAMPLE 9-1: SAVING STATUS AND W REGISTERS USING GENERAL PURPOSE RAM (0x20 - 0x6F)

```
MOVWF    W_TEMP           ;Copy W to TEMP register, could be bank one or zero
SWAPF    STATUS,W         ;Swap status to be saved into W
BCF      STATUS,RP0       ;Change to bank zero, regardless of current bank
MOVWF    STATUS_TEMP      ;Save status to bank zero STATUS_TEMP register
:
:(ISR)
:
SWAPF    STATUS_TEMP,W    ;Swap STATUS_TEMP register into W
                          ;(sets bank to original state)
MOVWF    STATUS           ;Move W into STATUS register
SWAPF    W_TEMP,F         ;Swap W_TEMP
SWAPF    W_TEMP,W         ;Swap W_TEMP into W
RETFIE                    ;Return from interrupt
```

EXAMPLE 9-2: SAVING STATUS AND W REGISTERS USING SHARED RAM (0x70 - 0x7F)

```
MOVWF    W_TEMP           ;Copy W to TEMP register (bank independent)
MOVF     STATUS,W         ;Move STATUS register into W
MOVWF    STATUS_TEMP      ;Save contents of STATUS register
:
:(ISR)
:
MOVF     STATUS_TEMP,W    ;Retrieve copy of STATUS register
MOVWF    STATUS           ;Restore pre-isr STATUS register contents
SWAPF    W_TEMP,F         ;
SWAPF    W_TEMP,W         ;Restore pre-isr W register contents
RETFIE                    ;Return from interrupt
```

10.1 Special Function Registers as Source/Destination

The PIC12C67X's orthogonal instruction set allows read and write of all file registers, including special function registers. There are some special situations the user should be aware of:

10.1.1 STATUS AS DESTINATION

If an instruction writes to STATUS, the Z, C and DC bits may be set or cleared as a result of the instruction and overwrite the original data bits written. For example, executing `CLRF STATUS` will clear register STATUS, and then set the Z bit leaving `0000 0100b` in the register.

10.1.2 TRIS AS DESTINATION

Bit 3 of the TRIS register always reads as a '1' since GP3 is an input only pin. This fact can affect some read-modify-write operations on the TRIS register.

10.1.3 PCL AS SOURCE OR DESTINATION

Read, write or read-modify-write on PCL may have the following results:

Read PC:	PCL → dest
Write PCL:	PCLATH → PCH; 8-bit destination value → PCL
Read-Modify-Write:	PCL→ ALU operand PCLATH → PCH; 8-bit result → PCL

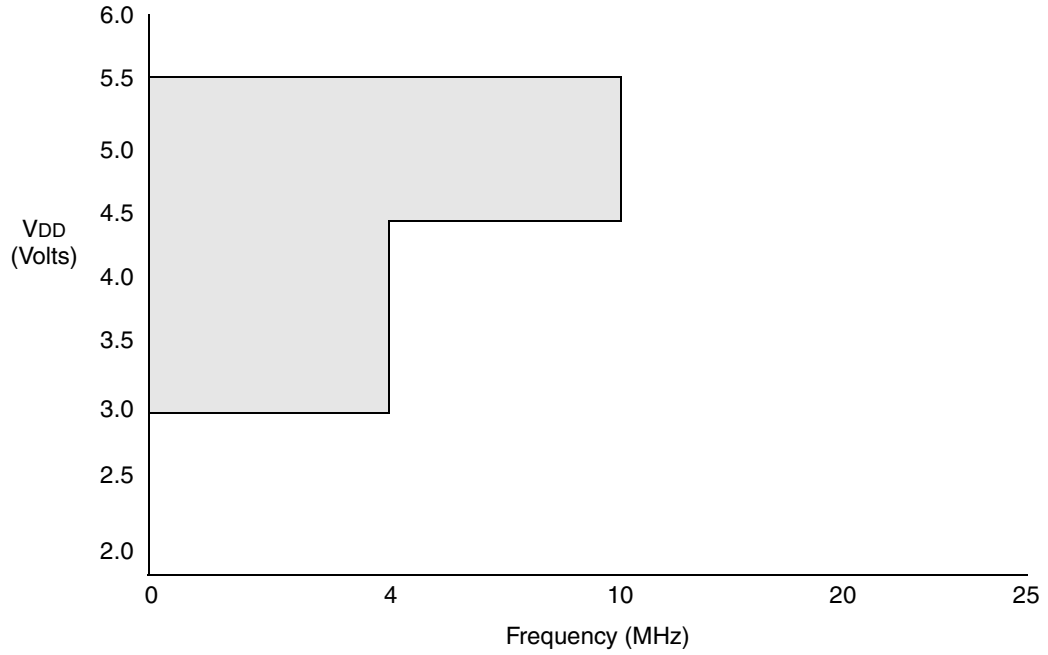
Where PCH = program counter high byte (not an addressable register), PCLATH = Program counter high holding latch, dest = destination, WREG or f.

10.1.4 BIT MANIPULATION

All bit manipulation instructions are done by first reading the entire register, operating on the selected bit and writing the result back (read-modify-write). The user should keep this in mind when operating on special function registers, such as ports.

NOTES:

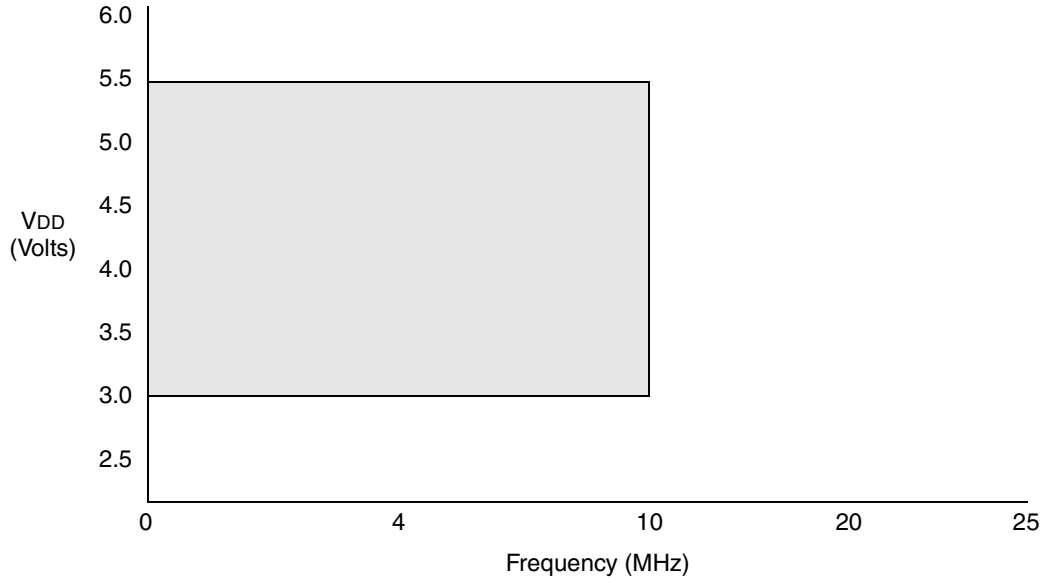
FIGURE 12-1: PIC12C67X VOLTAGE-FREQUENCY GRAPH, -40°C ≤ TA < 0°C, +70°C <TA ≤ +125°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

FIGURE 12-2: PIC12C67X VOLTAGE-FREQUENCY GRAPH, 0°C ≤ TA ≤ +70°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

12.1 DC Characteristics: PIC12C671/672 (Commercial, Industrial, Extended) PIC12CE673/674 (Commercial, Industrial, Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C (commercial) –40°C ≤ TA ≤ +85°C (industrial) –40°C ≤ TA ≤ +125°C (extended)				
Parm No.	**Characteristic**	**Sym**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
D001	**Supply Voltage**	VDD	3.0		5.5	V	
D002	**RAM Data Retention Voltage(2)**	VDR		1.5*		V	Device in SLEEP mode
D003	**VDD Start Voltage to ensure Power-on Reset**	VPOR		VSS		V	See section on Power-on Reset for details
D004	**VDD Rise Rate to ensure Power-on Reset**	SVDD	0.05*			V/ms	See section on Power-on Reset for details
D010	**Supply Current(3)**	IDD	—	1.2	2.5	mA	FOSC = 4MHz, VDD = 3.0V XT and EXTRC mode (Note 4)
D010C			—	1.2	2.5	mA	FOSC = 4MHz, VDD = 3.0V INTRC mode (Note 6)
			—	2.2	8	mA	FOSC = 10MHz, VDD = 5.5V HS mode
D010A			—	19	29	µA	FOSC = 32kHz, VDD = 3.0V, WDT disabled LP mode, Commercial Temperature
			—	19	37	µA	FOSC = 32kHz, VDD = 3.0V, WDT disabled LP mode, Industrial Temperature
			—	32	60	µA	FOSC = 32kHz, VDD = 3.0V, WDT disabled LP mode, Extended Temperature
D020	**Power-down Current(5)**	IPD	—	0.25	6	µA	VDD = 3.0V, Commercial, WDT disabled
D021			—	0.25	7	µA	VDD = 3.0V, Industrial, WDT disabled
D021B			—	2	14	µA	VDD = 3.0V, Extended, WDT disabled
			—	0.5	8	µA	VDD = 5.5V, Commercial, WDT disabled
			—	0.8	9	µA	VDD = 5.5V, Industrial, WDT disabled
			—	3	16	µA	VDD = 5.5V, Extended, WDT disabled
D022	**Watchdog Timer Current**	ΔIWDT	—	2.2	5	µA	VDD = 3.0V, Commercial
			—	2.2	6	µA	VDD = 3.0V, Industrial
			—	4	11	µA	VDD = 3.0V, Extended
D028	**Supply Current(3)** During read/write to EEPROM peripheral	ΔIEE	—	0.1	0.2	mA	FOSC = 4MHz, VDD = 5.5V, SCL = 400kHz For PIC12CE673/674 only

* These parameters are characterized but not tested.

Note 1: Data in Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

2: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

3: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD,
$\overline{MCLR}$ = VDD; WDT disabled.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode.

4: For EXTRC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula:
Ir = VDD/2REXT (mA) with REXT in kOhm.

5: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

6: INTRC calibration value is for 4MHz nominal at 5V, 25°C.

12.4 DC CHARACTERISTICS: PIC12LC671/672 (Commercial, Industrial) PIC12LCE673/674 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating temperature 0°C ≤ TA ≤ +70°C (commercial) –40°C ≤ TA ≤ +85°C (industrial) Operating voltage VDD range as described in DC spec Section 12.1 and Section 12.2.				
Param No.	**Characteristic**	**Sym**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	Input Low Voltage						
	I/O ports	VIL					
D030	with TTL buffer		VSS	—	0.8V	V	For 4.5V ≤ VDD ≤ 5.5V
			VSS	—	0.15VDD	V	otherwise
D031	with Schmitt Trigger buffer		VSS	—	0.2VDD	V	
D032	$\overline{MCLR}$, GP2/T0CKI/AN2/INT (in EXTRC mode)		VSS	—	0.2VDD	V	
D033	OSC1 (in EXTRC mode)		VSS	—	0.2VDD	V	Note 1
D033	OSC1 (in XT, HS, and LP)		VSS	—	0.3VDD	V	Note 1
	Input High Voltage						
	I/O ports	VIH		—			
D040	with TTL buffer		2.0V	—	VDD	V	4.5V ≤ VDD ≤ 5.5V
D040A			0.25VDD + 0.8V	—	VDD	V	otherwise
D041	with Schmitt Trigger buffer		0.8VDD	—	VDD	V	For entire VDD range
D042	$\overline{MCLR}$, GP2/T0CKI/AN2/INT		0.8VDD	—	VDD	V	
D042A	OSC1 (XT, HS, and LP)		0.7VDD	—	VDD	V	Note 1
D043	OSC1 (in EXTRC mode)		0.9VDD	—	VDD	V	
	Input Leakage Current (Notes 2, 3)						
D060	I/O ports	IIL	—	—	±1	µA	Vss ≤ VPIN ≤ VDD, Pin at hi-impedance
D061	GP3/$\overline{MCLR}$ (Note 5)				±30	µA	Vss ≤ VPIN ≤ VDD
D061A	GP3 (Note 6)				±5	µA	Vss ≤ VPIN ≤ VDD
D062	GP2/T0CKI		—	—	±5	µA	Vss ≤ VPIN ≤ VDD
D063	OSC1		—	—	±5	µA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
D070	GPIO weak pull-up current (Note 4)	IPUR	50	250	400	µA	VDD = 5V, VPIN = VSS
	$\overline{MCLR}$ pull-up current	—	—	—	30	µA	VDD = 5V, VPIN = VSS
	Output Low Voltage						
D080	I/O ports	VOL	—	—	0.6	V	IOL = 8.5 mA, VDD = 4.5V, –40°C to +85°C
D080A			—	—	0.6	V	IOL = 7.0 mA, VDD = 4.5V, –40°C to +125°C
D083	OSC2/CLKOUT		—	—	0.6	V	IOL = TBD, VDD = 4.5V, –40°C to +85°C
D083A			—	—	0.6	V	IOL = TBD, VDD = 4.5V, –40°C to +125°C

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In EXTRC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC12C67X be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

4: Does not include GP3. For GP3 see parameters D061 and D061A.

5: This spec. applies to GP3/$\overline{MCLR}$ configured as external $\overline{MCLR}$ and GP3/$\overline{MCLR}$ configured as input with internal pull-up enabled.

6: This spec. applies when GP3/$\overline{MCLR}$ is configured as an input with pull-up disabled. The leakage current of the $\overline{MCLR}$ circuit is higher than the standard I/O logic.

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating temperature 0°C ≤ TA ≤ +70°C (commercial) –40°C ≤ TA ≤ +85°C (industrial) Operating voltage VDD range as described in DC spec Section 12.1 and Section 12.2.				
Param No.	**Characteristic**	**Sym**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	Output High Voltage						
D090	I/O ports (Note 3)	VOH	VDD - 0.7	—	—	V	IOH = -3.0 mA, VDD = 4.5V, –40°C to +85°C
D090A			VDD - 0.7	—	—	V	IOH = -2.5 mA, VDD = 4.5V, –40°C to +125°C
D092	OSC2/CLKOUT		VDD - 0.7	—	—	V	IOH = TBD, VDD = 4.5V, –40°C to +85°C
D092A			VDD - 0.7	—	—	V	IOH = TBD, VDD = 4.5V, –40°C to +125°C
	Capacitive Loading Specs on Output Pins						
D100	OSC2 pin	COSC2	—	—	15	pF	In XT and LP modes when external clock is used to drive OSC1.
D101	All I/O pins	CIO	—	—	50	pF	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In EXTRC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC12C67X be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

4: Does not include GP3. For GP3 see parameters D061 and D061A.

5: This spec. applies to GP3/$\overline{MCLR}$ configured as external $\overline{MCLR}$ and GP3/$\overline{MCLR}$ configured as input with internal pull-up enabled.

6: This spec. applies when GP3/$\overline{MCLR}$ is configured as an input with pull-up disabled. The leakage current of the $\overline{MCLR}$ circuit is higher than the standard I/O logic.

13.0 DC AND AC CHARACTERISTICS - PIC12C671/PIC12C672/PIC12LC671/ PIC12LC672/PIC12CE673/PIC12CE674/PIC12LCE673/PIC12LCE674

The graphs and tables provided in this section are for design guidance and are not tested. In some graphs or tables the data presented are outside specified operating range (i.e., outside specified VDD range). This is for information only and devices will operate properly only within the specified range.

The data presented in this section is a statistical summary of data collected on units from different lots over a period of time. "Typical" represents the mean of the distribution while "max" or "min" represents (mean + 3σ) and (mean – 3σ) respectively, where σ is standard deviation.

FIGURE 13-1: CALIBRATED INTERNAL RC FREQUENCY RANGE VS. TEMPERATURE (VDD = 5.0V) (INTERNAL RC IS CALIBRATED TO 25°C, 5.0V)

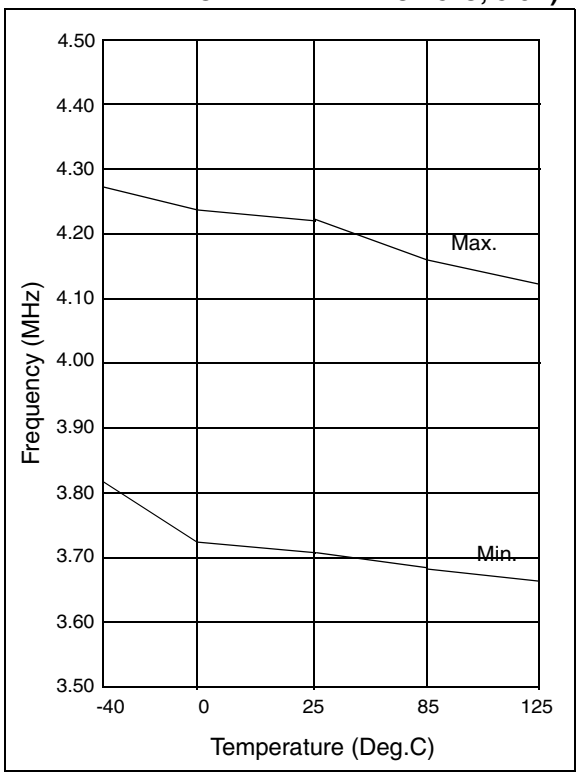
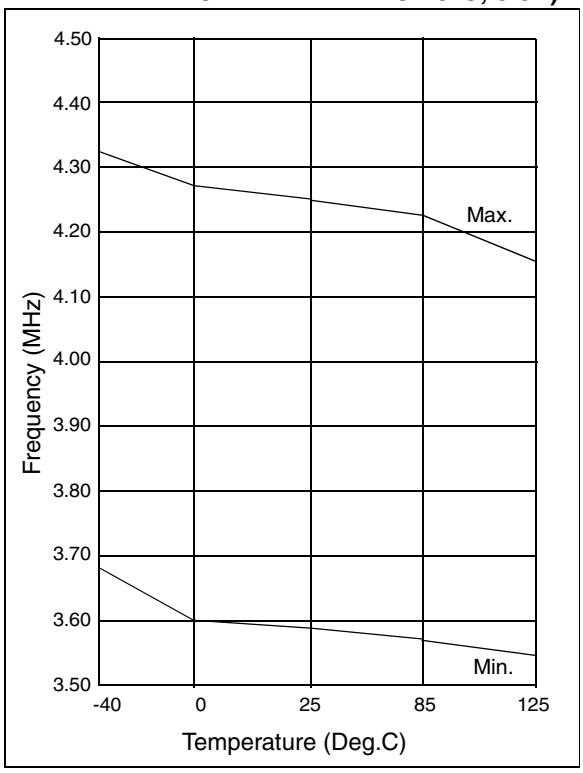


FIGURE 13-2: CALIBRATED INTERNAL RC FREQUENCY RANGE VS. TEMPERATURE (VDD = 2.5V) (INTERNAL RC IS CALIBRATED TO 25°C, 5.0V)



PIC12C67X PRODUCT IDENTIFICATION SYSTEM

PART NO. -XX X /XX XXX

Pattern:	Special Requirements	
Package:	P	= 300 mil PDIP
	JW	= 300 mil Windowed Ceramic Side Brazed
	SM	= 208 mil SOIC
Temperature Range:	-	= 0°C to +70°C
	I	= -40°C to +85°C
	E	= -40°C to +125°C
Frequency Range:	04	= 4 MHz/200 kHz
	10	= 10 MHz
Device	PIC12CE673 PIC12CE674 PIC12LCE673 PIC12LCE674 PIC12C671 PIC12C672 PIC12C671T (Tape & reel for SOIC only) PIC12C672T (Tape & reel for SOIC only) PIC12LC671 PIC12LC672 PIC12LC671T (Tape & reel for SOIC only) PIC12LC672T (Tape & reel for SOIC only)	

Examples

a) PIC12CE673-04/P Commercial Temp., PDIP Package, 4 MHz, normal VDD limits

b) PIC12CE673-04I/P Industrial Temp., PDIP package, 4 MHz, normal VDD limits

c) PIC12CE673-10I/P Industrial Temp., PDIP package, 10 MHz, normal VDD limits

d) PIC12C671-04/P Commercial Temp., PDIP Package, 4 MHz, normal VDD limits

e) PIC12C671-04I/SM Industrial Temp., SOIC package, 4 MHz, normal VDD limits

f) PIC12C671-04I/P Industrial Temp., PDIP package, 4 MHz, normal VDD limits

* JW Devices are UV erasable and can be programmed to any device configuration. JW Devices meet the electrical requirement of each oscillator type (including LC devices).

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Worldwide Site (www.microchip.com)